

Thermal Technology Development for the ARTEMIS Initiative (ARTEMIS-T)

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Program: FY22 R&TD Strategic Initiative

Strategic Focus Area: Architecture for Thermal Enclosure of Moon Instrument Suites - Strategic Initiative Leader: Ying Lin

PROJECT OBJECTIVES (FY20-FY22)

PRIMARY: Develop passive (radioisotope-free) lunar instrument thermal enclosure architecture for operation over multiple lunar day/night temp/power cycles **SECONDARY-1:** Develop carrier-independent, extended-life thermal enclosure designs for lunar magnetometers, seismometers, and IR spectrometers **SECONDARY-2:** Infuse PALETTE GCD project technologies including thermally-switched enclosures, spacerless MLI, thermal isolators, Vectran tension cables **RATIONALE:** Provide JPL with **Strategic Competitive Advantage** in responding to lunar instrument AOs, as extended-life capability will likely be highly valued **FY22 OBJECTIVES**

1. Complete the design/fabrication of a lunar magnetometer thermal enclosure (LMTE) for thermally managing the ARTEMIS-M Vector He Magnetometer (VHM) 2. Conduct a 36-day TVAC test to verify LMTE/VHM lunar day/night performance (conducted in JPL Building 125/B87)

3. Ensure that the LMTE/VHM system is ready to submit as a stand-alone lunar instrument proposal in the very near future

BACKGROUND

In FY19, the submitted ARTEMIS-T SR&TD and PALETTE NASA GCD proposals were nearly identical, thinking (at most) just one would be awarded
However, both were indeed awarded, creating a need to re-plan ARTEMIS-T for project differentiation

As directed by JPL 4X management, ARTEMIS-T changed course to Instrument Accommodation; PALETTE stayed on its Technology Development course
 The two projects have proceeded in parallel over the last 3 years, with significant achievements on both projects

APPROACH TO EXTENDED-LIFE LUNAR OPERATION ON LIMITED-LIFE CLPS LANDERS

- Add C&DH, power, telecom, and batteries to a science payload (SP) and mount all that equipment within an internal housing (IH)
- Conductively isolate the IH from an external housing (EH) using Vectran tension cables (VTC) and conductively isolate the EH from the carrier
- Radiatively isolate the SP using nested boxes of double-aluminized Mylar hanging from the VTCs, which is known as "Spacerless MLI"
- Thermally link the IH to the radiator with a Reverse-Operation DTE Thermal Switch (ROD-TSW) in series with a propylene mini-LHP

APPROACH TO MEETING ARTEMIS-T FY22 OBJECTIVES

- Design, build, assemble, and integrate the list of items in the table directly below this panel labeled "DESIGN/BUILD ELEMENTS"
 To overcome a high supplier quote, ARTEMIS-T built a mini-LHP (which did not work); as a backup, the design was modified to accept the PALETTE mini-LHP
- Overall assembly benefited from previous PALETTE experience, including building internal/external housings (IH/EH) out of corner/rail pieces as a cost-saver

TEST REQUIREMENTS		JIREMENTS	TEST METHODOLOGY
Subsystem	Item	Requirements (path to flight)	HOT Case
ARTEMIS-T	Int./Ext. Housings (IH/EH)	IH fits ARTEMIS-M + FSS non-payload items	TVAC CHAMBER 1. SHROUD AT 280 K
	ROD-TSW Thermal Switch	273 K actuation, 5 W/K ON, 0.002 W/K OFF	SHROUD 3 E=2.25 W
	Propylene Mini-LHP	Function as loop thermosyphon or mini-LHP	4. S = 0.15 W
	Vectran tension cables (VTC)	11/36 kN operating/ultimate load	MINI-LHP 5. 9 = 0.15 W
	Spacerless MLI (SMLI)	e* < 0.002 (between IH and EH)	6. Ø, € AS NEEDED*
	Conventional MLI (CMLI)	e* < 0.02 (outside of EH and rigid tube)	
	Thermal Isolating Mounts (Ti64)	G < 0.01 W/K, 50 kg instrument, GEVS	
	Solar Panel Simulator	Provides appropriate cold case heat leak path	PC 1. SHROUD AT 90 K
	Rigid Sensor Tube	0W, -173C/100C op, -183C/110C n-op	C4 C
	Heaters/Temp Sensors	Sufficient to simulate flight instrument	GSE 3. E = 2.25 W
ARTEMIS-M	VHM Sensor	0.3W, -30C/80C op, -40C/100C n-op	60 4 . S=0.15W
	VHM Electronics Box	3.9W/1.4W, 0C/40C op, -20/50C n-op	$\mathbf{TI64} \mathbf{TI64} TI$
	GSE Cables C1, C2, C3, C4	< 0.02 W/K,-173C/100C op, -183C/110C n-op	$\begin{array}{c c c c c c c c c c c c c c c c c c c $
TVAC I&T	Integration Plate	Integration plate rests on shroud bottom	C3 C2 AM transmission
	Shroud (LN2, CC Cooling)	LMTE test assembly fits within shroud	C1 GSE * FOR STARTUP/RESTART ** FOR SENSOR SURVIVAL
TEST SETUP		SETUP	TEST PROFILE
Six (6) Power Supplies Needed for ARTEMIS-T Heaters Below 1. Elec Box Simulator 3 Minco HK6900, 0.5" x 1", 210/3 ohms 3. Encrementer Structure 2 Advices HK6900, 0.5" x 1", 210/3 ohms			HOT Cycle Shroud = 280 K Q_{IH} = 10.3 W $Q_{sensors}$ = 0.3 W 280 K Cycle 1 280 K Cycle 2 280 K Cycle 3 280 K Cycle 4 280 K Cycle 5 280 K Cycle 5 280 K Cycle 6 280 K Cycle 7

 Incorporating the VHM sensor/electronics was a joint effort with ARTEMIS-M requiring building/integrating the set of cables (C1-C4) in the diagram below RESULTS

Test results for COLD cycles 2-4, and HOT cycles 3-4 are provided below in the results panel along with discussions of the thermal behavior of the system
 The system provided totally passive thermal control of VHM sensor/electronics except for brief periods of user intervention as described on the results panel
 SIGNIFICANCE → JPL NOW HAS A DISTINCT STRATEGIC COMPETITIVE ADVANTAGE IN PROPOSING EXTENDED-LIFE LUNAR INSTRUMENTS
 ARTEMIS-T seismometer thermal enclosure design was instrumental in JPL winning the \$40M Farside Seismic Suite (FSS) proposal
 FSS will take the Mars Insight-based VBB and SP seismometers to the lunar farside in 2025 (PI-Mark Panning, Deputy PI-Sharon Kedar)
 ARTEMIS-T magnetometer thermal enclosure design will be proposed very soon in response to a new lunar instrument AO (PI-Carol Raymond)
 Other lunar opportunities from ARTEMIS-T include LuSEE-Night led by UC Berkeley (PI-Stuart Bale) and LCRT, led by JPL (PI-Saptarshi Bandyopadhyay)
 ACKNOWLEDGMENTS → KEY PERSONNEL THAT HAVE CONTRIBUTED MIGHTILY TO ARTEMIS-T (AND ARTEMIS-M) SUCCESS
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 Management: Satish Khanna, Ying Lin, Tim O'Donnell, Brian Lim, Garry Burdick, Sabrina Feldman, Virgil Mireles, Gani Ganapathi, Chuck Phillips





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Publications:

- 1. Bugby, D., Rivera, J., and Lin, Y., "Instrument Thermal Management for Lunar Night Survival without Radioisotopes", 50th International Conference on Environmental Systems, ICES-2021-414, 12-15 July 2021.
- 2. Bugby, D., Rivera, J., Britton, S., "Lunar Night Survivability of Science Payloads Using PALETTE Thermal Technologies", 2022 Spacecraft Thermal Control Workshop, On-Line Virtual Meeting, 24-26 May 2022.
- 3. Bugby, D., Rivera, J., Britton, S., "Lunar Night Survivability of Cryocooled Instruments Using PALETTE Thermally-Switched Enclosures", International Cryocooler Conference (ICC), Bethlehem, PA, 27-30 June 2022.
- 4. Bugby, D., Rivera, J., Britton, S., "Planetary and Lunar Environment Thermal Toolbox Elements (PALETTE) Project Year Two Results", 2022 International Conference on Environmental Systems (ICES), St. Paul, MN, 10-14 July 2022.
- 5. Bugby, D., "Passive Thermal Management Technologies for Lunar Day/Night Survivability", Lunar Surface Innovation Consortium, Low Temperature Sub-kW Power and Energy Storage for the Lunar Surface Workshop, 28 July 2022.
- 6. Bugby, D., Rivera, J., "Lunar Night Survivable Architecture for Self-Sufficient Science Payloads", International Planetary Probe Workshop (IPPW 2022), Santa Clara, CA, 29 August to 2 September 2022.

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